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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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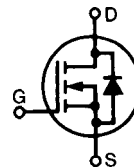
HiPerFET™ Power MOSFETs Q-Class

IXFH 20N60Q
IXFT 20N60Q

$V_{DSS} = 600 \text{ V}$
 $I_{D25} = 20 \text{ A}$
 $R_{DS(on)} = 0.35 \text{ } \Omega$

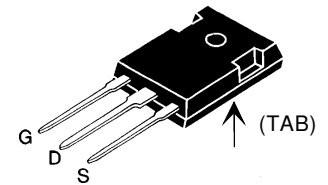
$t_{rr} \leq 250 \text{ ns}$

N-Channel Enhancement Mode
Avalanche Rated, High dv/dt,
Low Gate Charge and Capacitances



| Symbol | Test Conditions | Maximum Ratings | |
|-----------|--------------------------------------------------------------------------------------------------------------------------------------------------|-----------------|------------------|
| V_{DSS} | $T_J = 25^\circ\text{C}$ to 150°C | 600 | V |
| V_{DGR} | $T_J = 25^\circ\text{C}$ to 150°C ; $R_{GS} = 1 \text{ M}\Omega$ | 600 | V |
| V_{GS} | Continuous | ± 30 | V |
| V_{GSM} | Transient | ± 40 | V |
| I_{D25} | $T_C = 25^\circ\text{C}$ | 20 | A |
| I_{DM} | $T_C = 25^\circ\text{C}$, pulse width limited by T_{JM} | 80 | A |
| I_{AR} | $T_C = 25^\circ\text{C}$ | 20 | A |
| E_{AR} | $T_C = 25^\circ\text{C}$ | 30 | mJ |
| E_{AS} | $T_C = 25^\circ\text{C}$ | 1.5 | J |
| dv/dt | $I_S \leq I_{DM}$, $di/dt \leq 100 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$, $R_G = 2 \text{ } \Omega$ | 15 | V/ns |
| P_D | $T_C = 25^\circ\text{C}$ | 300 | W |
| T_J | | -55 ... +150 | $^\circ\text{C}$ |
| T_{JM} | | 150 | $^\circ\text{C}$ |
| T_{stg} | | -55 ... +150 | $^\circ\text{C}$ |
| T_L | 1.6 mm (0.062 in.) from case for 10 s | 300 | $^\circ\text{C}$ |
| M_d | Mounting torque | 1.13/10 | Nm/lb.in. |
| Weight | TO-247 AD | 6 | g |
| | TO-268 | 4 | g |

TO-247 AD (IXFH)



TO-268 (IXFT) Case Style



G = Gate
S = Source
D = Drain
TAB = Drain

Features

- IXYS advanced low gate charge process
- International standard packages
- Low gate charge and capacitance
 - easier to drive
 - faster switching
- Low $R_{DS(on)}$
- Unclamped Inductive Switching (UIS) rated
- Molding epoxies meet UL 94 V-0 flammability classification

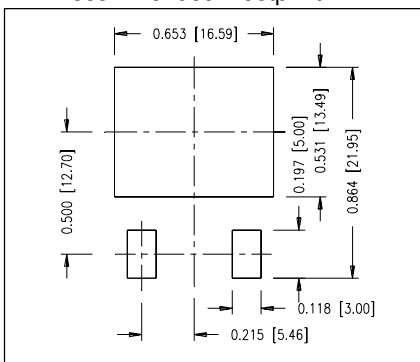
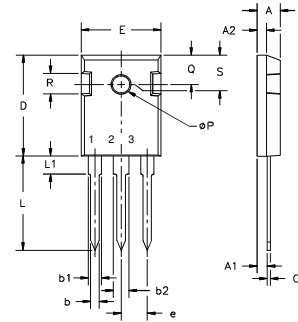
Advantages

- Easy to mount
- Space savings
- High power density

| Symbol | Test Conditions ($T_J = 25^\circ\text{C}$, unless otherwise specified) | Characteristic Values | | |
|--------------|--------------------------------------------------------------------------------------------------------------------------|-----------------------|------|----------------------|
| | | Min. | Typ. | Max. |
| V_{DSS} | $V_{GS} = 0 \text{ V}$, $I_D = 250 \text{ } \mu\text{A}$ | 600 | | V |
| $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 4 \text{ mA}$ | 2.0 | | V |
| I_{GSS} | $V_{GS} = \pm 30 \text{ V}_{DC}$, $V_{DS} = 0$ | | | $\pm 100 \text{ nA}$ |
| I_{DSS} | $V_{DS} = V_{DSS}$, $T_J = 25^\circ\text{C}$ | | | 25 μA |
| | $V_{GS} = 0 \text{ V}$, $T_J = 125^\circ\text{C}$ | | | 1 mA |
| $R_{DS(on)}$ | $V_{GS} = 10 \text{ V}$, $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300 \text{ } \mu\text{s}$, duty cycle $d \leq 2\%$ | | | 0.35 Ω |

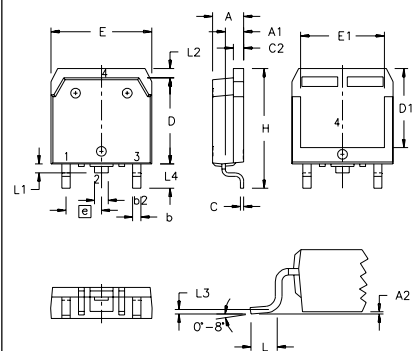
| Symbol | Test Conditions | Characteristic Values | | | |
|---------------------------|---------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------|------|------|-----|
| | | (T _J = 25°C, unless otherwise specified) | | | |
| | | Min. | Typ. | Max. | |
| g_{fs} | V _{DS} = 10 V; I _D = 0.5 I _{D25} , pulse test | 10 | 20 | S | |
| C_{iss} | V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz | | 3300 | pF | |
| C_{oss} | | | | | |
| C_{rss} | | | | | |
| t_{d(on)} | V _{GS} = 10 V, V _{DS} = 0.5 V _{DSS} , I _D = 0.5 I _{D25} R _G = 1.5 Ω (External) | | 20 | ns | |
| t_r | | | | | |
| t_{d(off)} | | | | | |
| t_f | | | | | |
| Q_{g(on)} | V _{GS} = 10 V, V _{DS} = 0.5 V _{DSS} , I _D = 0.5 I _{D25} | | 90 | nC | |
| Q_{gs} | | | | | |
| Q_{gd} | | | | | |
| R_{thJC} | (TO-247) | | 0.25 | 0.42 | K/W |
| R_{thCK} | | | | | K/W |

| Symbol | Test Conditions | Characteristic Values | | | |
|-----------------------|--------------------------------------------------------------------------------------------------------|-----------------------------------------------------|------|------|----|
| | | (T _J = 25°C, unless otherwise specified) | | | |
| | | min. | typ. | max. | |
| I_S | V _{GS} = 0 V | | | 20 | A |
| I_{SM} | Repetitive; pulse width limited by T _{JM} | | | 80 | A |
| V_{SD} | I _F = I _S , V _{GS} = 0 V, Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 % | | | 1.5 | V |
| t_{rr} | I _F = I _S , -di/dt = 100 A/μs, V _R = 100 V | | 0.85 | 250 | ns |
| Q_{RM} | | | | | μC |
| I_{RM} | | | | 8 | A |

Min Recommended Footprint

TO-247 AD Outline


Terminals: 1 - Gate 2 - Drain
3 - Source Tab - Drain

| Dim. | Millimeter | | Inches | |
|----------------|------------|-------|--------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.7 | 5.3 | .185 | .209 |
| A ₁ | 2.2 | 2.54 | .087 | .102 |
| A ₂ | 2.2 | 2.6 | .059 | .098 |
| b | 1.0 | 1.4 | .040 | .055 |
| b ₁ | 1.65 | 2.13 | .065 | .084 |
| b ₂ | 2.87 | 3.12 | .113 | .123 |
| C | .4 | .8 | .016 | .031 |
| D | 20.80 | 21.46 | .819 | .845 |
| E | 15.75 | 16.26 | .610 | .640 |
| e | 5.20 | 5.72 | 0.205 | 0.225 |
| L | 19.81 | 20.32 | .780 | .800 |
| L ₁ | | 4.50 | | .177 |
| ∅P | 3.55 | 3.65 | .140 | .144 |
| Q | 5.89 | 6.40 | 0.232 | 0.252 |
| R | 4.32 | 5.49 | .170 | .216 |
| S | 6.15 | BSC | 242 | BSC |

TO-268 Outline


| SYM | INCHES | | MILLIMETERS | |
|----------------|----------|------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | .193 | .201 | 4.90 | 5.10 |
| A ₁ | .106 | .114 | 2.70 | 2.90 |
| A ₂ | .001 | .010 | 0.02 | 0.25 |
| b | .045 | .057 | 1.15 | 1.45 |
| b ₂ | .075 | .083 | 1.90 | 2.10 |
| C | .016 | .026 | 0.40 | 0.65 |
| C ₂ | .057 | .063 | 1.45 | 1.60 |
| D | .543 | .551 | 13.80 | 14.00 |
| D ₁ | .488 | .500 | 12.40 | 12.70 |
| E | .624 | .632 | 15.85 | 16.05 |
| E ₁ | .524 | .535 | 13.30 | 13.60 |
| e | .215 BSC | | 5.45 BSC | |
| H | .736 | .752 | 18.70 | 19.10 |
| L | .094 | .106 | 2.40 | 2.70 |
| L ₁ | .047 | .055 | 1.20 | 1.40 |
| L ₂ | .039 | .045 | 1.00 | 1.15 |
| L ₃ | .010 BSC | | 0.25 BSC | |
| L ₄ | .150 | .161 | 3.80 | 4.10 |

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715 6,306,728B1 6,259,123B1 6,306,728B1
4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025 6,404,065B1 6,162,665 6,534,343

Fig. 1. Output Characteristics
@ 25 Deg. C

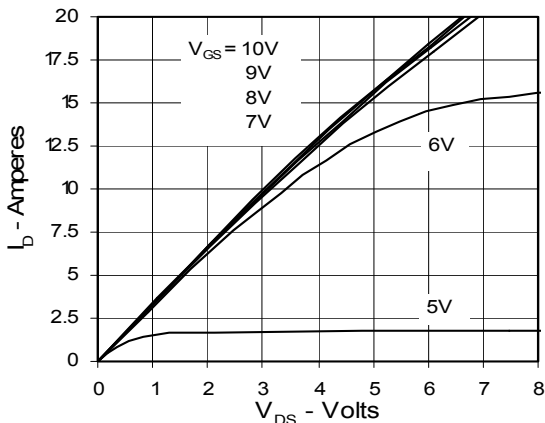


Fig. 2. Extended Output Characteristics
@ 25 deg. C

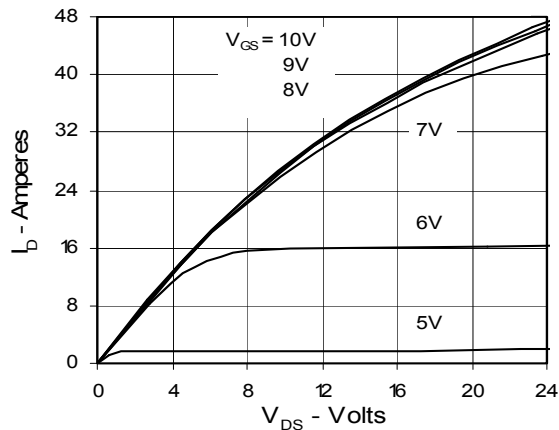


Fig. 3. Output Characteristics
@ 125 Deg. C

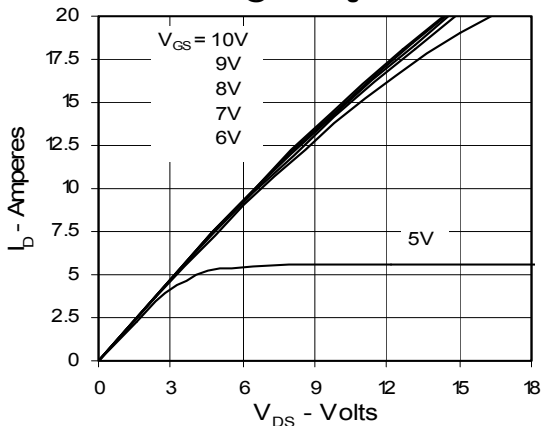


Fig. 4. $R_{DS(on)}$ Normalized to I_{D25} Value vs. Junction Temperature

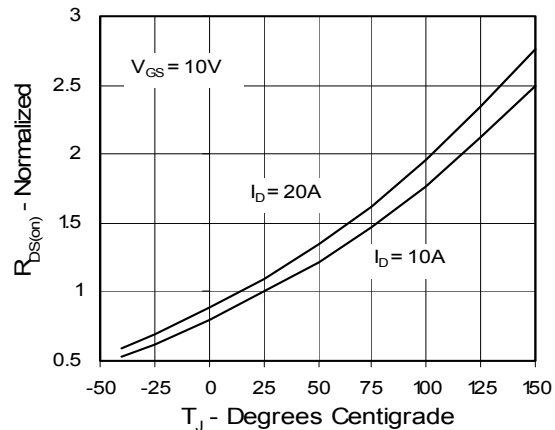


Fig. 5. $R_{DS(on)}$ Normalized to I_{D25} Value vs. I_D

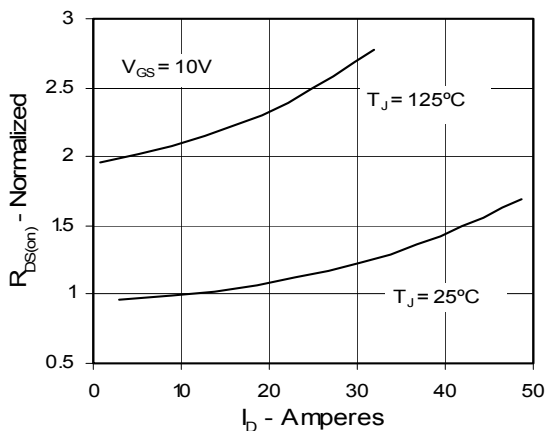


Fig. 6. Drain Current vs. Case Temperature

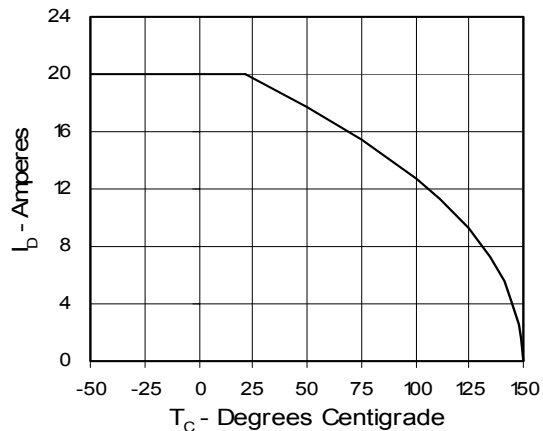


Fig. 7. Input Admittance

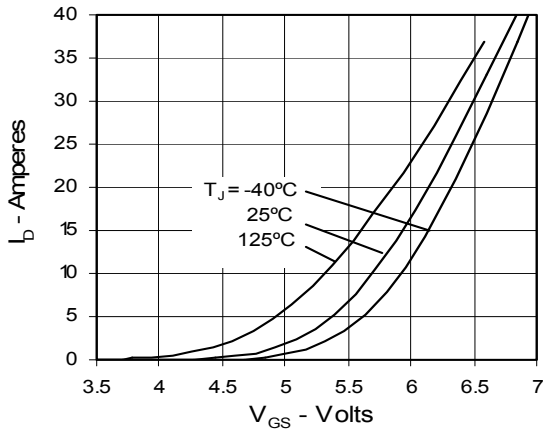


Fig. 8. Transconductance

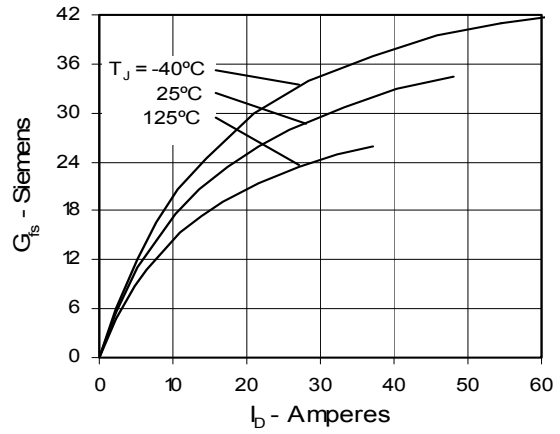


Fig. 9. Source Current vs. Source-To-Drain Voltage

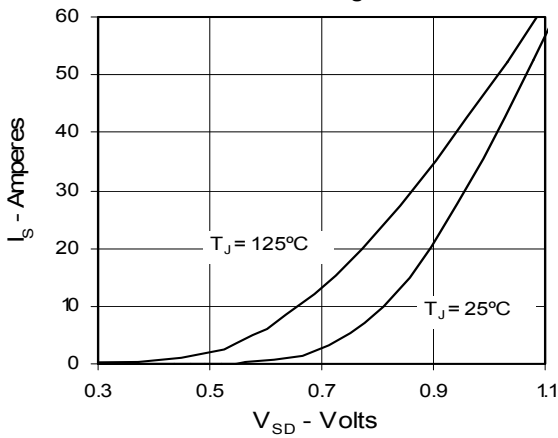


Fig. 10. Gate Charge

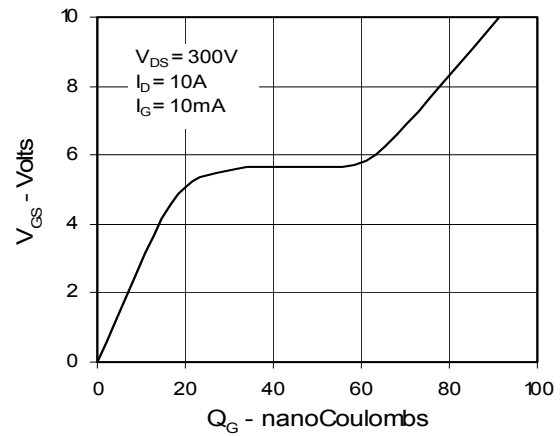


Fig. 11. Capacitance

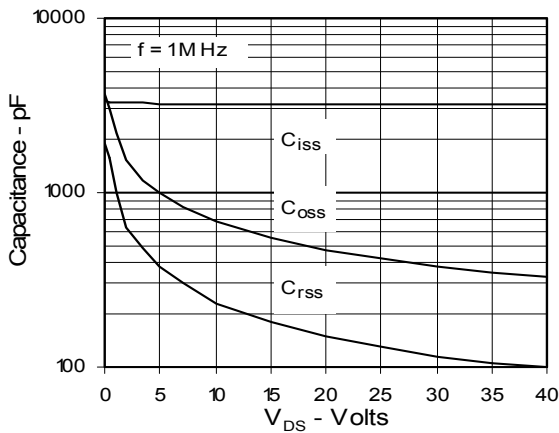
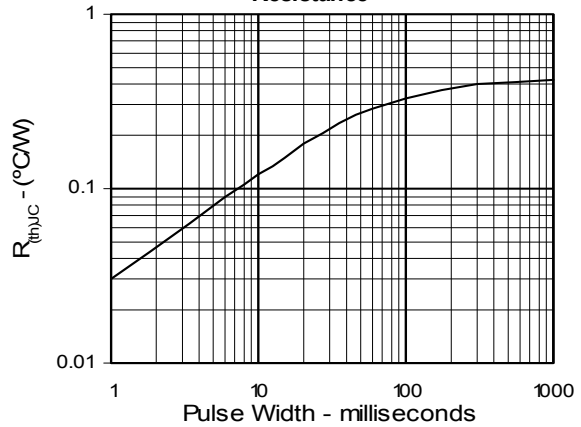


Fig. 12. Maximum Transient Thermal Resistance



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